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TFT | CHARACTER | UWVD | FSC | SEGMENT | CUSTOM | REPLACEMENT

TFT Display Module

Part Number E40RC-FS1000-N

Overview:

- 4.0-inch TFT (77x80mm)
- MIPI/DSI Interface
- 16.7M colors
- 480x480 pixels
- White LED back-light

- Transmissive/ Normally Black
- No Touch Panel
- 1000 NITS
- Controller: ST7701S
- RoHS Compliant



Description

This is a color active matrix TFT (Thin Film Transistor) LCD (Liquid Crystal Display) that uses amorphous silicon TFT as a switching device. This model is composed of a transmissive type TFT-LCD Panel, driver circuit and backlight unit. The resolution of the 4.0" TFT-LCD contains 480x480 pixels and can display up to 16.7M colors.

Features

Low Input Voltage: 3.3V (TYP) Display Colors: 16.7M colors TFT Interface: MIPI/DSI

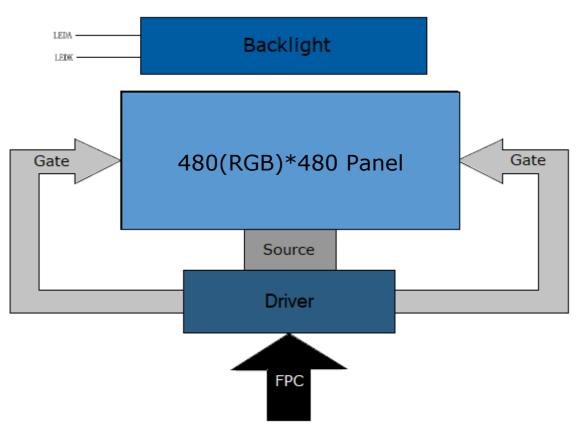
General Information Items	Specification Main Panel	Unit	Note
TFT Display Area (AA)	71.86(H) x 70.18(V) (3.95 inch)	mm	-
Driver Element	TFT active matrix	-	-
Display Colors	16.7M	colors	-
Display Resolution	480(RGB)x480	pixels	-
TFT Pixel Arrangement	RGB stripe	-	-
Pixel Pitch	0.1497(H)*0.1462(V)	mm	-
Viewing Angle	ALL	o'clock	-
TFT Controller IC	ST7701S	-	-
LCM Interface	2-lane MIPI	-	-
Display Mode	Transmissive/Normally Black	-	-
Operating Temperature	-30~+85	°C	-
Storage Temperature	-40~+90	°C	-

Mechanical Information

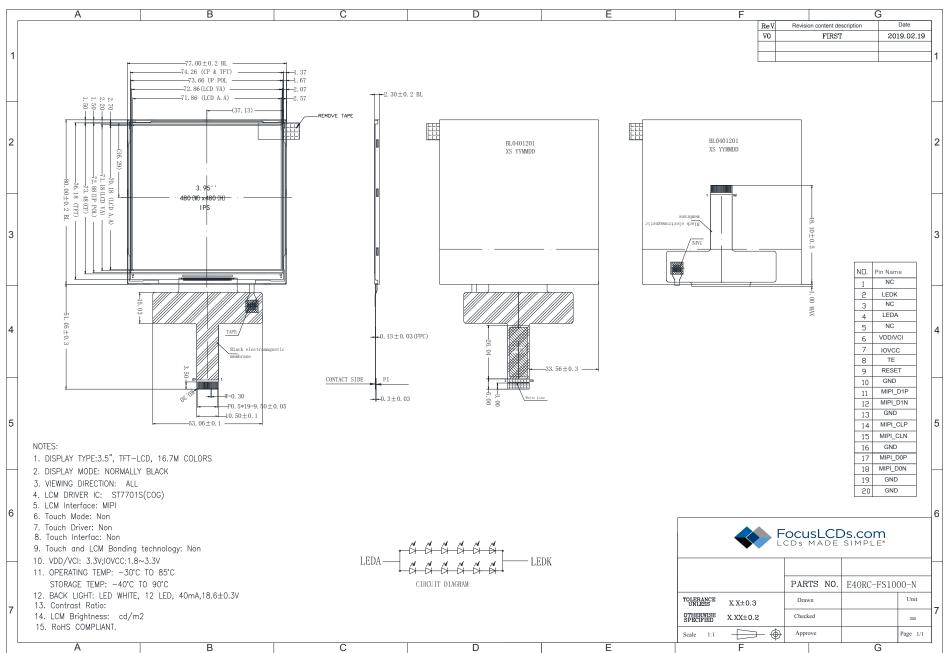
	ltem	Min	Тур.	Max	Unit	Note
Madula	Height (H)		77		mm	-
Module Size	Vertical (V)		80		mm	-
0120	Depth (D)		2.3		mm	-
	Weight		TBD		g	-



1. Block Diagram



2. Outline Dimensions





3. Input TFT Terminal Pin Assignment

Recommended Connector: FH19C-20S-0.5SH(10)

NO.	Symbol	Description	I/O
1	NC	-	
2	LEDK	Cathode pin of backlight	Р
3	NC	-	
4	LEDA	Anode pin of backlight	Р
5	NC	-	
6	VDD/VCI	Supply voltage (3.3V)	Р
7	IOVCC	I/O power supply voltage	Р
8	TE	Tearing effect output. Leave pin open when not used.	0
9	RESET	External reset input. Initializes the chip with low input. Execute a power on reset	1
9	RESET	after applying power.	1
10	GND	Ground	Р
11	MIPI_D1P	MIPI DSI differential data pair (DSI-Dn+/-)	I/O
12	MIPI_D1N		I/O
13	GND	Ground	Р
14	MIPI_CLP	MIPI DSI differential clock pair (DSI-CLK+/-)	I
15	MIPI_CLN		I
16	GND	Ground	Р
17	MIPI_D0P	MIRI DSI differential data pair (DSI Dp. ()	I/O
18	MIPI_DON	MIPI DSI differential data pair (DSI-Dn+/-)	I/O
19	GND	Ground	Р
20	GND	Ground	Р
· Input	0. Outnut P. P	oluger	

I: Input, O: Output, P: Power



4. LCD Optical Characteristics

4.1 Optical Specifications

ltem		Symbol	Condition	Min	Тур.	Max	Unit	Note
Contrast R	atio	Cr		640	800			(2)
	Rising	To To			25	25		(4)
Response Time	Falling	Tr+Tf			25	35	ms	(4)
Uniform	ity	S(%)		55	60		%	(5)
	White	W _x	Normal	0.269	0.309	0.349		
	White	W _Y	Viewing Angle	0.310	0.350	0.390		
	Red	R _x	θ=0	0.571	0.611	0.651		(5)(6)
Color Filter	neu	Ry		0.323	0.363	0.403		
Chromaticity	Green	G _x		0.277	0.317	0.357		
	Green	Gy		0.530	0.570	0.610		
	Blue	B _x		0.110	0.150	0.190	-	
	Diac	B _Y		0.060	0.100	0.140		
	Hor.	ΘL		70	80			
Viewing Angle		Θr	CR>10	70	80		dograa	
Viewing Angle	Ver.	Θτ	CU>10	70	80		degree	(1)(6)
	VCI.	Θв		70	80			
Option View [Direction			ALL				(1)

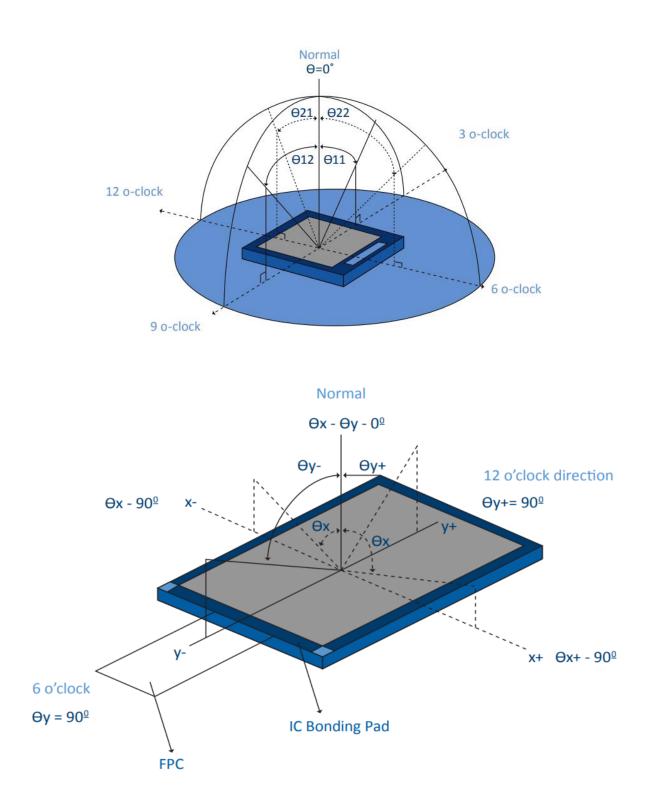
4.2 Measuring Conditions

Measuring surrounding: dark room Ambient temperature: 25±2°C 15 min. warm-up time



Optical Specification Reference Notes:

(1) Definition of Viewing Angle: The viewing angle is the angle at which the contrast ratio is greater than 10. The viewing angles are determined for the horizontal or 3,9 o'clock direction and the vertical or 6,12 o'clock direction with respect to the optical axis which is normal to the LCD surface.

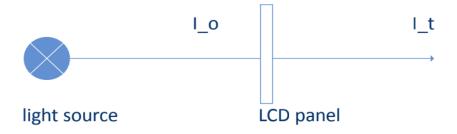




(2) Definition of Contrast Ratio (Cr): measured at the center point of panel. The contrast ratio (Cr) measured on a module, is the ratio between the luminance (Lw) in a full white area (R=G=B=1) and the luminance (Ld) in a dark area (R=G=B=0).

$$Cr = \frac{Lw}{Ld}$$

(3) Definition of transmittance (T%): The transmittance of the panel including the polarizers is measured with electrical driving.

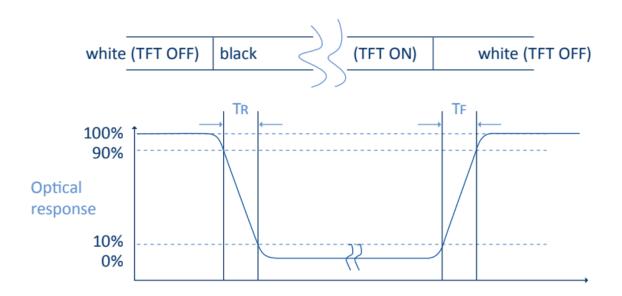


The transmittance is defined as:

$$Tr = \frac{It}{Io} x \ 100\%$$

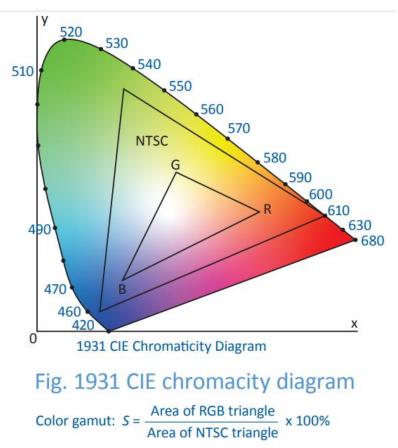
Io = the brightness of the light source. It = the brightness after panel transmission

(4) Definition of Response Time (Tr, Tf): The rise time 'Tr' is defined as the time for luminance to change from 90% to 10% as a result of a change of the electrical condition. The fall time 'Tf' is defined as the time for luminance to change from 10% to 90% as a result of a change of the electrical condition.

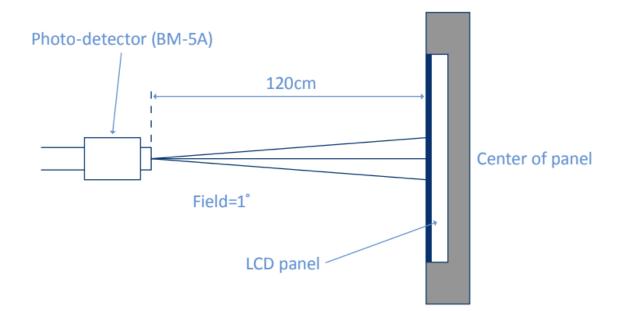




(5) Definition of Color Gamut: Measuring machine CFT-01. NTSC's Primaries: R(x,y,Y),G(x,y,Y), B(x,y,Y). FPM520 of Westar Display Technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.



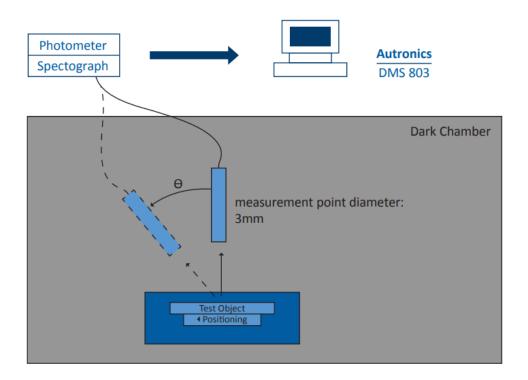
(6) Definition of Optical Measurement Setup:



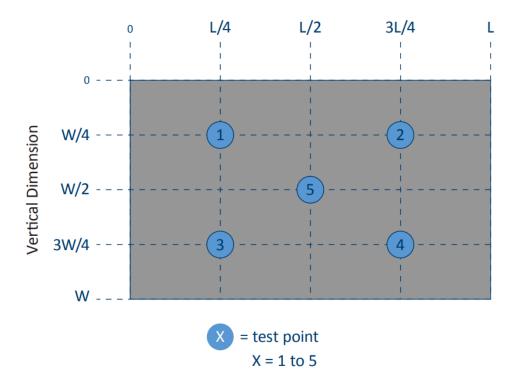


(6) Optical Measurement Setup Continued:

The LCD module should be stabilized at a given temperature for 20 minutes to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting backlight for 20 minutes.



Horizontal Dimension





5. Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 °C, VSS=0V)

Characteristics	Symbol	Min	Max	Unit
Digital Supply Voltage	Vci	-0.3	4.6	V
Digital Interface Supply Voltage	IOVcc	-0.3	4.6	V
Operating Temperature	Тор	-30	+85	°C
Storage Temperature	Тѕт	-40	+90	°C

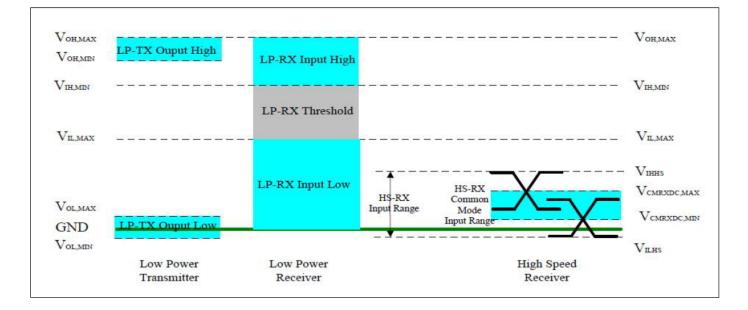
NOTE: If the absolute maximum rating of the above parameters is exceeded, even momentarily, the quality of the product may be degraded. Absolute maximum ratings specify the values which the product may be physically damaged if exceeded. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min	Тур.	Max	Unit	Note
Digital Supply Voltage	VCI	2.5	3.3	3.6	V	
Digital Interface Supply Voltage	IOVCC	1.65	1.8	3.3	V	
Normal Mode Current	IDD		30		mA	
Differential Input High Threshold Voltage	VIT+		0	50	mV	
Differential Input Low Threshold Voltage	VIT-	-50	0		mV	MIPI_CLK MIPI_Data
Single-ended Receiver Input Operation Voltage Range	VIR	0.5		1.2	V	



5.3 MIPI DC Electrical Characteristics



Characteristics	Symbol	Min	Тур.	Max	Unit			
Operation Voltage for MIPI Receiver								
Low power mode operating voltage	Vlph	1.1	1.2	1.3	V			
MIPI Charac	teristics for High	n Speed Red	eiver					
Single ended input low voltage	VILHS	-40			mV			
Single ended input high voltage	VIHHS			460	mV			
Common mode voltage	VCMRXDC	70		330	mV			
Differential input impedance	Zid	80	100	125	Ω			
MIPI Chara	acteristics for Lo	w Power M	ode					
Pad signal voltage range	VI	-50		1350	mV			
Logic 0 input threshold	VIL	0		550	mV			
Logic 1 input threshold	Viн	880		1350	mV			
Output low level	Vol	-50		50	mV			
Output high level	Vон	1.1	1.2	1.3	V			



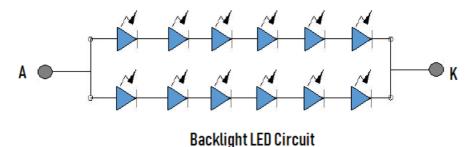
5.4 LED Backlight Characteristics

ltem	Symbol	Min	Тур.	Max	Unit	Note
Forward Current	IF	35	40		mA	
Forward Voltage	VF		18.6		V	
LCM Luminance	LV	950	1000		cd/m2	Note 3
LED lifetime	Hr		50000		hour	Note1 & 2
Uniformity	AVg	80			%	Note 3

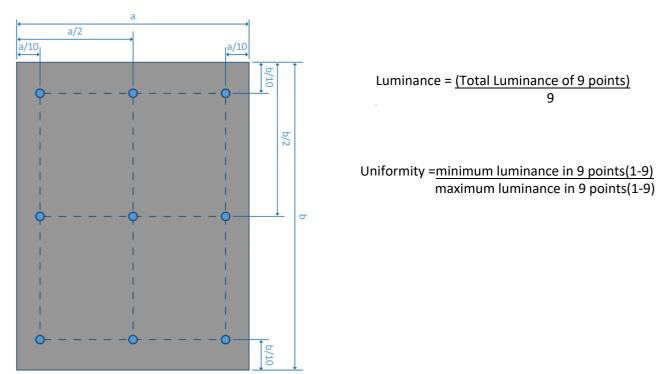
The back-light system is edge-lighting type with 12 chips White LED

Note 1: LED lifetime (Hr) can be defined as the time in which it continues to operate under the condition: Ta=25±3 °C, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The "LED lifetime" is defined as the module brightness decrease to 50% original brightness at Ta=25°C and IL=40mA. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.



Note 3: Luminance Uniformity of these 9 points is defined as below:





6. MIPI Interface AC Characteristics

6.1 High Speed Mode

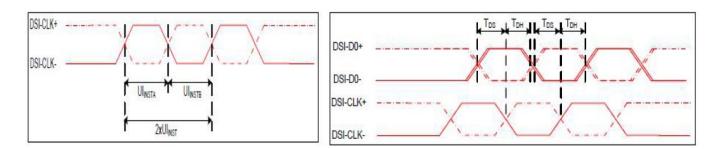


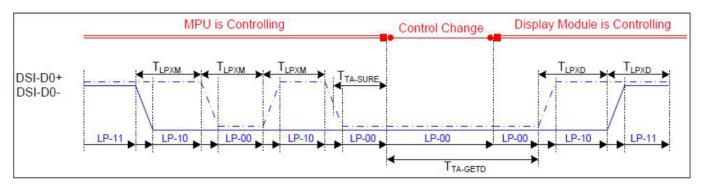
Figure 6.1: DSI Clock Channel Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Note
DSI-CLK+/-	2xUIINSTA	Double UI Instantaneous	4	25	ns	
DSI-CLK+/-	UIINSTA UIINSTB	UI Instantaneous Halves	2	12.5	ns	UI=UIINSTA=UIINSTB
DSI-Dn+/-	tDS	Data to clock setup time	0.15		UI	
DSI-Dn+/-	tDH	Data to clock hold time	0.15		UI	

Table 6.1: MIPI Interface High Speed Mode Timing Characteristics



6.2 Low Power Mode





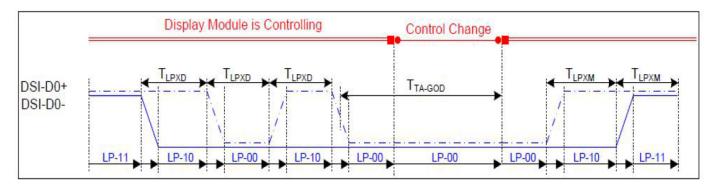


Figure 6.3: Buss Turnaround (BTA) from MPU to Display Module Timing Diagram

Signal	Symbol	Parameter	Min	Max	Unit	Note
DSI-D0+/-	TLPXM	Length of LP-00, LP_01, LP-10 or LP-11 periods MPU-> Display Module	50	75	ns	Input
DSI-D0+/-	TLPXD	Length of LP-00, LP_01, LP-10 or LP-11 periods MPU-> Display Module	50	75	ns	Output
DSI-D0+/-	TTA-SURED	Time-out before the MPU starts driving	Tlpxd	2xTlpxd	ns	Output
DSI-D0+/-	TTA-GETD	Time to drive LP-00 by display module	5xT	LPXD	ns	Input
DSI-D0+/-	TTA-GOD	Time to drive LP-00 after turnaround request-MPU	4xT	LPXD	ns	Output

Table 6.2: MIPI Interface Low Power Mode Timing Characteristics



6.3 Bursts Mode

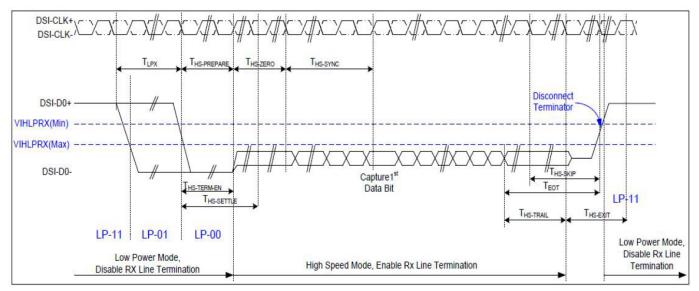


Figure 6.4: Data Lanes Low Power Mode to/from High Speed Mode Timing Diagram

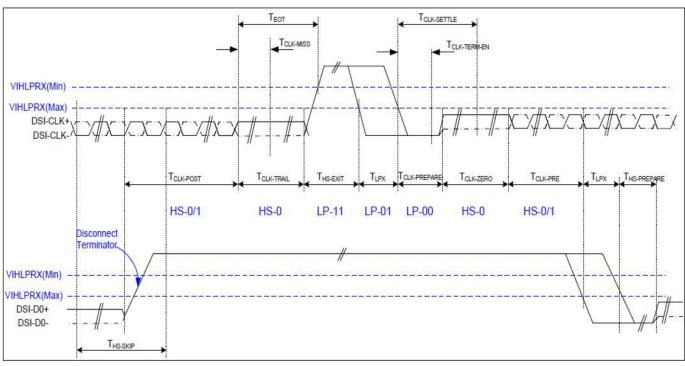


Figure 6.5: Clock Lanes High Speed Mode to/from Low Power Mode Timing Diagram



Signal	Symbol	Parameter	Min	Max	Unit	Note
	L	ow Power Mode to High Speed Mode	e Timing			
DSI-Dn+/-	TLPX	Length of any low power state period	50		ns	Input
DSI-Dn+/-	THS-PREPARE	Time to drive LP-00 to prepare for HS transmission	40+4UI	85+6UI	ns	Input
DSI-Dn+/-	THS-TERM-EN	Time to enable data receiver line termination measured from when Dn crosses VILMAX		35+4UI	ns	Input
DSI-Dn+/-	THS-PREPARE+ THS-ZERO	THS-PREPARE+time to drive HS-0 before the sync sequence	140+10UI		ns	Input
	F	ligh Speed Mode to Low Power Mode	e Timing			
DSI-Dn+/-	THS-SKIP	Time-out at display module to ignore transition period of EoT	40	55+4UI	ns	Input
DSI-Dn+/-	THS-EXIT	Time to drive LP-11 after HS burst	100		ns	Input
DSI-Dn+/-	THS-TRIAL	Time to drive flipped differential state after last payload data bit of a HS transmission burst	60+4UI		ns	Input
	High	n Speed Mode to/from Low Power Mo	ode Timing	5		
DSI-CLK+/-	TCLK-POS	Time that the MPU shall continue sending HS clock after the last associated data lane has transitioned to LP mode	60+52UI		ns	Input
DSI-CLK+/-	TCLK-TRAIL	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60		ns	Input
DSI-CLK+/-	THS-EXIT	Time to drive LP-11 after HS burst	100		ns	Input
DSI-CLK+/-	TCLK-PREPARE	Time to drive LP-00 to prepare for Hs transmission	38	95	ns	Input
DSI-CLK+/-	TCLK-TERM-EN	Time out at clock ands display module to enable HS transmission		38	ns	Input
DSI-CLK+/-	TCLK-PREPARE+ TCLK-ZERO	Minimum lead HS-0 drive period before starting clock	300		ns	Input
DSI-CLK+/-	TCLK-PRE	Time that the HS clock shall be driven prior to any associated data lane beginning the transition from LP to HS mode	8UI		ns	Input
DSI-CLK+/-	TEOT	Time from start of TCLK-TRAIL period to start of LP-11 state		105+12 UI	ns	Input

Table 6.3: Bursts Mode LP to/from HS Mode Timing Characteristics



6.4 Reset Timing

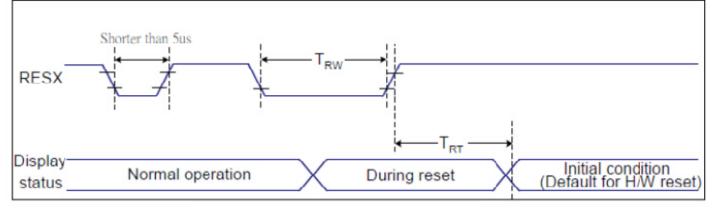


Figure 6.6: Reset Timing Diagram

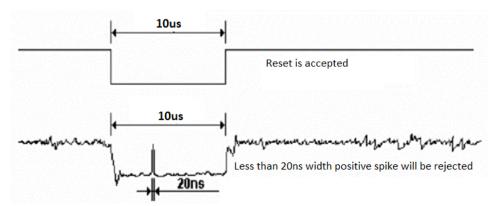
Related Pins	Symbol	Parameter	Min	Max	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TDT	Deceterized	-	5 (Note 1,5)	ms
	TRT	Reset cancel		120 (Note 1, 6, 7)	ms

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5ms after a rising edge of RESX.
- 2. Spike due to an electrostatic discharge on RESX line does not because irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9 us	Reset starts

- 3. During the resetting period, the display will be blanked (the display is entering blanking sequence, which maximum time is 120ms, when reset starts in Sleep Out mode. The display remains the blank state in Sleep in mode) and then return to Default condition for Hardware Reset.
- 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- 7. It is necessary to wait 5ms after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120ms.



7. Cautions and Handling Precautions

7.1 Handling and Operating the Module

- 1. When the module is assembled, it should be attached to the system firmly. Do not warp or twist the module during assembly work.
- 2. Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- 3. Note that polarizer is very fragile and could be easily damaged. Do not press or scratch thesurface.
- 4. Do not allow drops of water or chemicals to remain on the display surface. If you have the droplets for a long time, staining and discoloration may occur.
- 5. If the surface of the polarizer is dirty, clean it using some absorbent cotton or softcloth.
- 6. The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane. Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- 7. If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- 8. Protect the module from static; it may cause damage to the CMOS ICs.
- 9. Use fingerstalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- 10. Do not disassemble the module.
- 11. Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- 12. Pins of I/F connector shall not be touched directly with bare hands.
- 13. Do not connect, disconnect the module in the "Power ON" condition.
- 14. Power supply should always be turned on/off by the item Power On Sequence & Power Off Sequence.

7.2 Storage and Transportation.

- 1. Do not leave the panel in high temperature, and high humidity for a long time. It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- 2. Do not store the TFT-LCD module in direct sunlight.
- 3. The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- 4. It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module. In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- 5. This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.